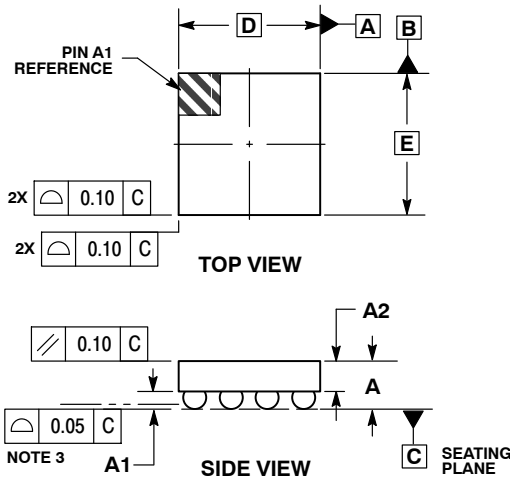




SCALE 4:1

WLCSP15, 1.56x1.56
CASE 567FX
ISSUE 0

DATE 07 JUN 2012

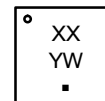


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

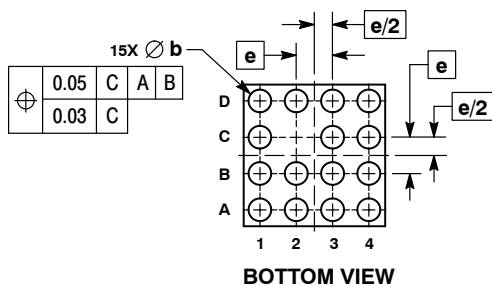
DIM	MILLIMETERS	
	MIN	MAX
A	0.47	0.53
A1	0.185	0.205
A2	0.305 REF	
b	0.24	0.29
D	1.56 BSC	
E	1.56 BSC	
e	0.40 BSC	

GENERIC MARKING DIAGRAM*

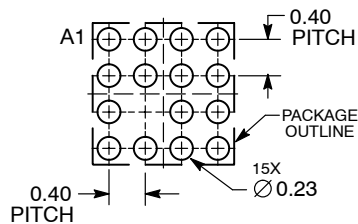


- XX = Specific Device Code
- Y = Year
- W = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP15, 1.56X1.56	PAGE 1 OF 1

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